	APPLICATION	FOR EXTENSION OF ESO	С ТЕ	CHNOLOGY FLO	W APPROVAL	Page 1
ESCC	Component Title:	Thin Film Technology Network Resistors, Fix	for C	Chip, Wraparo	und, Single and	Appl. No.
	Executive Member:	CNES		Date: 07/03	8/2025	287J
Technology Flow submitted for Extension	on of Qualification Ap	proval:				1
SUMMARY DESCRIPTION	TES	ST STRUCTURES		COMPONENTS	S PROPOSED FOR C	UALIFICATION
P : Single resistor 0402, 0603, 0805, 1206, 2010 chip PRA : 2 to 8 resistors of similar value, based on 0603 (PRA 100), 0805 (PRA135) or 1206 (PRA182) units CNW : 2 to 8 resistors with at leas two different values with the same form factor as PRA Substrate : Alumina Resistive layer : Nickel Chromium Protection : Silicium nitride Termination : Nickel Barrier Processes : Thin Film deposition Finish : SnPbAg or Au	P0402, P0603, with min., critic values, PRA100, PRA1 critical resistan t	P0805, P1206 and P20 cal resistance and max. 135, PRA182 with min., ce and max. values.	010	By form factor ESCC400102 ESCC400102 ESCC400102 ESCC400102 ESCC400102 ESCC400102 ESCC400102 (*) Note that g intended for d	-: 3 var. 15 and 13, 1 3 var. 01, 05 (*) an 3 var. 02, 06 (*) an 3 var. 03, 07 (*) an 3 var. 04, 08 (*) an 5 var. 01 to 07, 22 5 var. 08 to 14, 29 5 var. 15 to 21, 36 old finish variants a e-golding and tinni	4(*) d 09 d 10 d 11 d 12 to 28 to 35 to 42 are not ng
Component Manufacturer	2 Location of N	Ianufacturing Plant(s)	3	Date of original of	qualification approval:	4
VISHAY SA Division Résistances de Très	Nice (France)			Date: 1	5/02/2009	
Haute Précision				Certificate 2 Ref No.	87	
ESCC Specifications used for Maintenance testing:	5 Deviations to LV Specification use	T testing and Detail ed:	testing and Detail <u>6</u> Qualification Extension Report reference and date:			
Generic: 4001 Issue: 5	No 🗆 Yes	⊠ (supply details Box 15)	in	QML Quality	Synthesis report	S:
Detail(s): 4001/023 Issue: 12	Deviation from c	urrent Specifications:		QML Synthe	sis 2024, 09/01/20 sis 2023 complet,	19/01/2024
4001/025 Issue: 8	No 🖂 Yes	□ (Supply details	;)			
Summary of procurement or equivalent	test results during cu	rrent validity period in supp	ort of	l this application (th	ose to ESCC listed fir	st) 8
Customer Componen	it LVT	Date code	e		Quantity Delivered	1
TAS PHR AVNET ALTER ECOMAL TTI				2023 : 115 2 2024 : 205 5	26 96	
TTI PRA / CNW TAS ALTER				2023 : 2459 2024 : 1385		
AVNET PFRR				2023 : 13 16	6	
TTI Charcorft Electronics Limited				2024 : 20 70	9	
PID changes since last maintenance of	qualification 9	Current PID Verified b	y:		CNES	10
None					Name of Excutive R	epresentative
Minor" 🛛 *Drevide detaile in	how	Ref No: PID-TFI) P PI		AE/40/20	24
	box.	Rev.:		L	ale. 13/10/20	124
		Date: 15/10/2	024			
Current Manufacturing facilities surveye	ed by: CNES			on	16/02/2023	11
	(Name o	f Executive Representative)		(Date)	
Satisfactory: Yes	No 🗆	Explain				
Report Reference: Fontaine-Visit 2023	2023.0003306-CR- e -Vishay-Fevrier-	_				

	APPLICAT	ION FOR EXTE	ENSION OF ESCC QUA	LIFICATIO	ON APPROVAL	Page	2
ESCC	Component title:	Thin Film Te Resistors, Fi	echnology for Chip, W ixed	raparound	I, Single and Network	Appl. N	lo.
	Executive Member:	CNES		Date:	07/03/2025	287	J
Failure Analysis, DPA, NCCS ava Ref. No's and purposes:	ilable: Yes	🗆 No	☑ (Supply data)				12
The undersigned hereby certifies on behalf that the appropriate documentation has be (except as stated in box 15;) - that the repo CNES as the responsible Executive Mem	of the ESCC Executiv en evaluated; - that ful rts and data are availa ber for ESCC qualifica	re - that the abo I compliance to able at the ESC tion status to b	ove information is correct all ESCC requirements C Executive and therefore e extended to the compo	t; - is evidence ore applies onent(s) lis	e on behalf of ted herein.		13
Date: 07/03/2025				(Się	L. FONTAINE, gnature of the Executive C	CNES Coordinator)	
Continuation of Boxes above: Box 6: Periodic Testing is defined in pa	ragraph 6 of the Tecl	nnology Flow	PID (See page 3)		Fontain Signatur numériq e Lya	re jue de e Lya)25.03.07 i +01'00'	14

Description Description April No. 2873 No: Or compliance to ESCC requirements: 15 No: Specification Paragraph Chart F4 Specification or restonais for socreptability of noncompliance to achieve full compliance for ESCC qualification or restonais for socreptability of noncompliance. Non compliance to achieve full compliance for ESCC qualification or restonais for socreptability of noncompliance. 16 Executive Manager Disposition Action / Remarks: 17 Action / Remarks: No 1 Date: No Digitally signed by Alit Zadeh Digitally signed by Alit Zadeh Date: No 1423332 4-01000 1423332 4-01000	APPLICATION FOR EXTENSION OF ESCC QUALIFICATION APPROVAL							
Executive Manager Disposition Application ESCC qualification or rationale for acceptability of monocrypterion 1st Additional tasks required to achieve full compliance for ESCC qualification or rationale for acceptability of monocrypterion 1st 1st	See.	ESCC	Component title:	Thin Film Technology for Resistors, Fixed	Chip, Wraparour	d, Single and Network	Appl. No.	
Non compliance to ESCC requirements: 13 No: Specification Paragraph Chart F4 setting proceed with the implementation of periodic testing as described in PID paragraph 6.3 Additional tasks required to achieve full compliance for ESCC qualification or nationale for acceptability of non-compliance. 16 Additional tasks required to achieve full compliance for ESCC qualification or nationale for acceptability of non-compliance. 16 None 14 Digitally signed by Ali Zadeh Ali Zadeh Digitally signed by Ali Zadeh Diate: 2025.03.20 Date: Digitally signed by Ali Zadeh Diate: 2025.03.20 14:23:32 -01/00'			Executive Member:	CNES	Date:	07/03/2025	287J	
No: Specification Paragraph Non compliance 1 4001 Chart F4 Chart F4 testing replaced with the in Pilo paragraph 5.3 Additional tests required to achieve full compliance for ESCC qualification or rationale for acceptability of noncompliance. 16 Additional tests required to achieve full compliance for ESCC qualification or rationale for acceptability of noncompliance. 16 None 17 17 Action / Remarks: 17 Action / Remarks: 17 Date: 202.03.20 Date: 12.23.24.01/201	Non com	pliance to ESCC requirements:					15	
1 4001 Chart F4 Enter F4 testing replaced in the implementation of periodic testing as described in PID paragraph 6.3 Additional tasks required to achieve full compliance for ESCC qualification or nationale for acceptability of noncompliance: 16 Additional tasks required to achieve full compliance for ESCC qualification or nationale for acceptability of noncompliance: 18 Executive Manager Disposition 17 Action / Remarks: 17 Action / Remarks: 17 Action / Remarks: 10 Date: 202:03.20 Date: 12:32:32.20	No.:	Specification		Paragraph		Non compliance)	
Additional tasks required to achieve full compliance for ESCC qualification or rationale for acceptability of None Executive Manager Disposition Application Approval: Yes No Action / Remarks: Digitally signed by Ali Zadeh Date: Digitally signed by Ali Zadeh Date: 2025.03.20 14:23:32 +01'00'	1	4001	Char	Paragraph t F4	Chart F implem in PID p	4 testing replaced with t entation of periodic testi baragraph 6.3	he ing as described	
None Executive Manager Disposition Application Approval: Yes ⊠ No □ Action / Remarks: Digitally signed by Ali Zadeh Date: Digitally signed by Ali Zadeh Date: 2025,03.20 14:23:32 +01'00'	Additiona	I tasks required to achieve full con	mpliance for ESCC q	ualification or rationale for acc	eptability of		16	
Line 17 Application Approval: Yes x No Action / Remarks: Digitally signed by Ali Zadeh Date: Digitally signed by 11 Zadeh Date: 2025.03.20 14:23:32 +01'00'								
Application Approval: Yes x No Action / Remarks: Digitally signed by Ali Zadeh Date: 2025.03.20 14:23:32 +01'00'	Executive	e Manager Disposition					17	
	Application Action / R	n Approval: Yes ⊠ Remarks:	No 🗆		Ali Za	Digitally Ali Zade Date: 20 14:23:32	/ signed by 2h 025.03.20 2 +01'00'	

APPLICATION FOR EXTENSION OF ESCC QUALIFICATION APPROVAL									
ESCC	Component Title:	Thin Film Technology for Chip, Resistors, Fixed	Wraparound, Sing	le and Network	Appl. No.				
	Executive Member:	CNES	Date:	07/03/2025	287J				
ANNEX 1: LIST OF TESTS DONE TO SUF	PORT EXTENSION	OF QUALIFICATION				18			
Tests conducted in compliance with:									
 ESCC 4001 generic specificati or PID-TFD P PRA CNW Issue Tests vehicle identification/description: 	on; Chart F4 (for ES0 e 12 (for ESCC/QML p	CC/QPL parts); parts)							
PHR 0603 : DC 2109 / 2235 / 2309 / 232 PHR 0805 : DC 2213 / 2221 / 2245 / 230 PHR 1206 : DC 2444 / 2309 / 2319 / 234 PHR 0402 : DC 2315 / 2346 / 2401 PHR 2010 : DC 2345	6 / 2403 9 / 2402 1								
PRAHR : DC 2340 / 2329									
Detail Specification reference: 40	01/023 & 4001/025								

Chart F4	Test	Tick when done	Conditions	Date Code	Teste d Qty	N° of Rejects	Comments if not performed Comments on Rejection
nical Subgroup (1)	Mounting	X	IEC 60115-1 clause 4.31	2109 2213 2221 2235 2245 2245 2244 2309 2309 2309 2315 2326 2319 2340 2329 2346 2341 2345 2401 2403 2402	5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5	0	
Environmental /Mecha	Rapid Change Of Temperature		IEC 60068-2-14	2109 2213 2221 2235 2245 2244 2309 2309 2309 2315 2326 2319 2340 2329 2346 2341 2345 2401 2403 2402	5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5	0	
	Vibration		IEC 60068-2-6		-		NA

	Climatic test Sequence	X	ESCC 4001, Para 8.10	2109 2213 2221 2235 2245 2244 2309 2309 2315 2326 2319 2346 2341 2345 2401 2403 2402	5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5	0	
	Seal Test		IEC 60068-2-17				NA
	Mounting		IEC 60115-1 clause 4.31	2109 2213 2221 2235 2245 2245 2309 2309 2315 2326 2319 2346 2341 2345 2401 2403 2402	2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2	0	
	Robustness of Terminations	X	IEC 60068-2-21	2109 2213 2221 2235 2245 2244 2309 2309 2309 2315 2326 2319 2346 2341 2345 2401 2403 2402	2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2	0	Adhesion followed with Substrate bending
ironmental /Mechanical Subgroup (2)	Climatic test Sequence		ESCC 4001, Para 8.10	2109 2213 2221 2235 2245 2244 2309 2309 2309 2315 2326 2319 2346 2341 2345 2401 2403 2402	2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2	0	
L L	Seal Test		IEC 60068-2-17				NA

	Resistance to Soldering Heat	IEC 60068-2-20	2109 2213 2221 2235 2245 2244 2309 2309 2309 2309 2315 2326 2319 2340 2329 2346 2341 2345 2401 2403 2402	2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2	0	
	Mounting	IEC 60115-1 clause 4.31	2109 2213 2221	222		
ronmental /Mechanical Subgroup (3)	Climatic test Sequence	ESCC 4001, Para 8.10	2109 2213 2221 2235 2245 2244 2309 2309 2309 2315 2326 2319 2346 2341 2345 2401 2403 2402	2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2	0	
Envi	Seal Test	IEC 60068-2-17				NA
	Mounting	IEC 60115-1 clause 4.31	2109 2213 2221 2235 2245 2244 2309 2309 2315 2326 2319	5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5		
Environmental /Mechanical Subgroup (4)	Insulation Resistance	ESCC 4001, Para 8.3.1.2	2109 2213 2221 2235 2245 2244 2309 2309 2309 2315 2326 2319 2340 2329 2346 2341 2345 2401 2403 2402	5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5	0	

		Voltage Proof	X	ESCC 4001, Para 8.3.1.3	2109 2213 2221 2235 2245 2244 2309 2309 2309 2315 2326 2319 2346 2341 2345 2401 2403 2402	5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5	0	
	đ	Mounting	\boxtimes	IEC 60115-1 clause 4.31	2109 2213 2221	5 5 5	0	(*) performed after Solderability / Permanence of Marking Sequence
	lurance Subgrou	Operating Life	×	ESCC 4001, Para 8.13	2221 2340 2329	5 10 10	0	PRAHR135 CNWHR2195 PHR Low Ohmic value PRAHR100 PRAHR135 PRAHR182
	End	Seal Test		IEC 60068-2-17				NA
-	nbly Capability Subgroup	Solderability		IEC 60068-2-20	2109 2213 2221 2235 2245 2244 2309 2309 2315 2326 2319 2340 2329 2346 2341 2345 2401 2403 2402	2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2	0	
	Assen	Permanence of marking	\boxtimes	ESCC 24800	2340 2329	5 5	0	PRA / CNW
	e Rate Endurance ↓ roup	Operating Life	×	ESCC 4001, Para 8.13	2221	5		2 000H 4 000H 6 000H 8 000H - 2000H 4000H 6000H 8000H
	Fail Sut	Seal Test		IEC 60068-2-17				NA
	Tests	High & Low Temp (Temperature Coefficient)		ESCC 4001			0	(*) performed before Rapid Change of Temperature
	onal							
	vdditi							
	¥							

		APPLICATI	ON FOR EXTENSION	OF ESCC QUALIFICATIO	ON APPROVAL	Page 6			
E	SCC	Component title:	Thin Film Technol Resistors, Fixed	ogy for Chip, Wraparoun	d, Single and Network	Appl. No.			
		Executive Member:	CNES	Date:	07/03/2025	287J			
NOTES ON THE COMPLETION OF THE APPLICATION FORM FOR ESCC QUALIFICATION EXTENSION APPROVAL									
ENTRIES Form heading shall indicate: - the title of the component as given in its detail specification or the name of the series, family; - the Executive Mem - the entering date; - the certificate number and its sequential suffix.									
Box 1	Box 1 shall provide details given in the table; in particular there shall be listed: - the variants or range of variants; - the range of componer (the ESCC code is recommended to indicate the values or values range, the tolerance, the voltage, etc); the designation given the detail specification as 'base on'; - under Test Vehicle enter either an ESCC code or the specific characteristic capable identifying the component tested (e.g., voltage of coil for a relay); - under component similar enter a cross if relevant.								
Box 2; 3 and 4	As per QPL entry;	otherwise, an explana	ation of the changes n	nust be supplied.					
Box 5	Will show the ES reported were per	CC Generic and Deta formed. If the specifica	ail specifications, inclu ations are different fro	ding issue number and re n those current on the date	evision letter, current at the of the application, see B	ne time the tests ox 6.			
Box 6	Will show the dev deviations this mu indicate also whet	iations from the Gene ist be listed in Box 15. ther the test data devia	ric and Detail Specific In case the referenced ates or not from such o	ations listed in Box 5, in pa I specification in Box 5 hav current documents.	articular deviations from te e currently a different issu	esting. In case of e and/or revision			
Box 7	Must reference the	e report(s) supplied in	support of the applica	tion.					
Box 8	Should provide the to the ESCC Exec	e details of procuremen cutive under the terms	nt to the full ESCC Sys of the relevant Gener	tem, documentation of all o c Specification. An approp	f which should already hav riate table has been drawi	ve been delivered n in this box.			
Box 9	If the PID evolved be provided toget	after the Original Qua her with the reasons fo	lification or after the la or the changes. Major	st Extension of Qualification changes shall be clearly m	on, adequate details of suc arked.	ch evolution shall			
Box 10	Identify the curren as close as possit	t PID issue status, date ble to the required date	e and actual date of ve e of extension.	ification. The date of verific	ation of the current PID sh	ould be arranged			
Box 11	This box can be of practices, procedu out in accordance	completed only after a ures, material, etc. use with the requirements	a physical visit to the d in manufacturing the s of ESCC Basic Spec	plant to confirm that no ur components are as descri fication No. 20200 and its	nexplained changes occur bed in the PID. This surve findings shall be recorded	rred and that the y shall be carried			
Box 12	Provide details of Nonconformance(satisfactory result	of, or reference to, a (s) (NCCS) occurred d s.	ny Destructive Physi luring the qualification	cal Analysis (DPA) and validity period, stating if es	Failure Analysis reports stablished corrective actio	as well as any n have produced			
Box 13	Enter only the na Coordinator.	me of the Executive	Member (i.e., CNES,	DLR, ESTEC, etc.) and the second s	ne signature of the respo	nsible Executive			
Box 14	To be used when the relevant Box.	there is a need to exp Box 14 can be broken	band any of the boxes into 14a, 14b, etc. if s	from 1 through 12. Identify everal boxes have to be ex	/ box affected and referen kpanded.	ice the Box 14 in			
Box 15	Fill in Table as rec	quested.							
Box 16	Any additional act by the ESCC Exe	tion deemed necessar cutive should be listed	y by the Executive Me herein or the reason(ember to bring the submitte s) to accept the noncomplia	ed data to a standard likel ance.	y to be accepted			
Box 17	All Executive Man entry, letters to the	ager recommendation e manufacturer, etc. sl	s on the application its hall be entered clearly	elf, special conditions or re in Box 19, signed by the re	strictions, modifications of epresentative for ESA, and	the QPL or QML dated.			
Box 18	Fill in Table as rec	quested.							
Box 19	Confidential Detai	ils of PID changes incl	uding those of a confi	dential nature, shall be prov	vided.				
Box 20	State noncomplia shall be sequentia	nce with reference to ally numbered. If releva	specification(s) and p ant state 'None'.	aragraph(s). To simplify re	eference in Box 16 each	nonconformance			
Box 21	Any additional act	tion deemed necessar cutive should be listed	y by the Executive Me herein or the reason(ember to bring the submitte s) to accept the noncomplia	ed data to a standard likel	y to be accepted			
Box 22	Additional Comme	ents.							